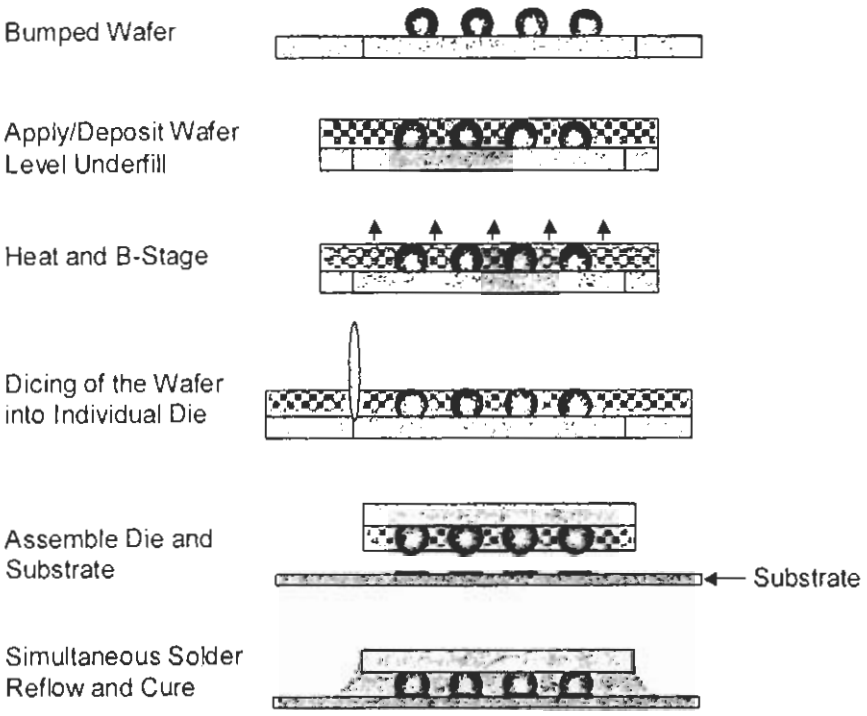


FIGURE 1: Current Pre-Applied Assembly Process

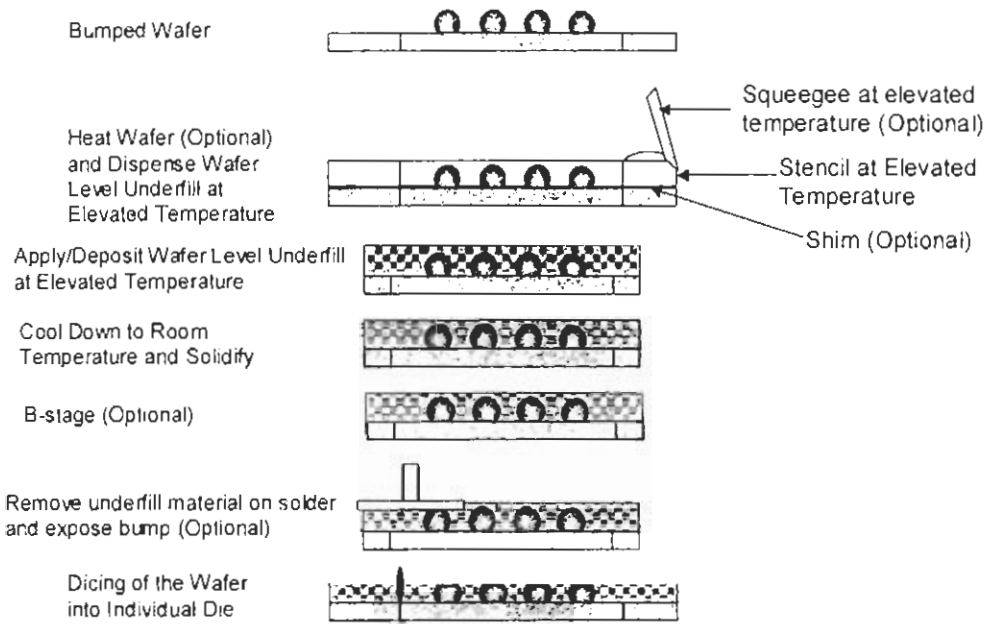


FIGURE 2: Hot Melt Printing Process and Removal of Underfill to Expose Bumps